1. Applying load to terminals during soldering under certain conditions may cause deformation and electrical property degradation.

2. Avoid use of water-soluble soldering flux, since it may corrode the switches.

3. Check and conform to soldering requirements under actual mass production conditions.

4. In soldering twice, make sure the solder joints should go down to normal temperature. Continuing heating will cause deformation of switch, loose and factored terminals, or may deteriorate electrical characteristics.

5. Flux from around and above the PC board should not adhere to the switches.

6. For the sizes of holes and patterns on a PC board for mounting a switch, refer to the recommended dimensions in the product drawings.

7. This switch is designed for manually operated units. Must not use this switch for a mechanical detection unit. For detection purposes, please use our detection switches.

8. After mounting the switches, if you intend to put the board into an oven in order to harden adhesive for other parts, please consult with Alps Alpine.

9. Use of a through-hole PC board, or a PC board of different thickness from the recommendation will have a different heat stress. Verify the soldering requirements thoroughly before use.

10. Solder the switches with detent at the detent position. Soldering switches fixed at the center of the detent may deform the detent mechanisms.

11. No washing.

12. Protect small and thin switches from external forces in the set mounting process.

13. Tighten the mounting screws by applying the specified torque. Tightening with a larger torque than the specified will result in malfunction or breakage of screws.

14. Use of the switches with voltage below 1V DC or current below 10μA may make contacts unstable. When using these switches in this way, consult with us beforehand.

15. The products are designed and manufactured for direct current resistance. Contact us for use of other resistances such as inductive (L) or capacitive (C).

16. The switch will be broken if impact force or a greater stress than that specified is applied. Take a great care not to let the switch be subject to greater stress than specified.

17. Do not apply a force from the side of the stem.

18. Be sure to push the center of switch for “without-stem” type. Extreme care is required for a hinge structure type because the stem press position moves when it is pressed.

19. Insert these switches to the specified mounting surface and mount them horizontally. If not mounted horizontally, these switches will malfunction.

20. Use of the switches in a dusty environment may lead the dusts entering through the openings and cause imperfect contact or malfunction. Take this into account for set design.

21. Corrosive gas if generated by peripheral parts of a set, malfunction such as imperfect contact may occur. Thorough investigation shall be required beforehand.

22. Be aware of dust intrusion into a non dustproof type TACT Switch™.

23. Storage

   ① Store the products as delivered, at a normal temperature and humidity, without direct sunshine and corrosive gas ambient. Use them at an earliest possible timing, not later than six months upon receipt.

   ② Store the key switches with the switch in the released position.